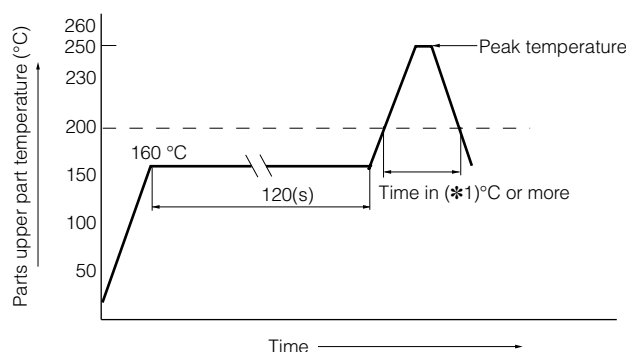


■ Reflow guaranteed condition

● RoHS compliant



Lead-Free reflow

Reflow No.	Fig. (1)	Fig. (2)	Fig. (3)	Fig. (4)
Category	φ3 to φ6.3	φ8 to φ10	φ12.5 to φ18	EB series (φ10 to φ18)
Peak temperature	250 °C	235 °C	230 °C (220 °C)	230 °C
Time in peak temperature	5 s	5 s	5 s (5 s)	5 s
Time in (*1) °C or more	≥200 °C 60 s	≥200 °C 60 s	≥200 °C 20 s (30 s)	≥200 °C 20 s
Time of reflow	1 time	1 time	1 time	1 time

High temperature Lead-Free reflow

Reflow No.	Fig. (5)	Fig. (6)		Fig. (7)		Fig. (8)	
Category	φ4 to φ6.3	φ8 to φ10		φ8 to φ10		φ6.3 to φ10 (TK · TP series)	
Peak temperature	260 °C (255 °C)	245 °C	260 °C	250 °C	260 °C	255 °C	260 °C
Time in peak temperature	≥250 °C 5 s (10 s)	≥240 °C 10 s	≥250 °C 5 s	≥240 °C 10 s	≥250 °C 5 s	≥250 °C 30 s	≥250 °C 20 s
Time in (*1) °C or more	≥230 °C 30 s	≥230 °C 30 s	≥230 °C 30 s	≥230 °C 30 s	≥230 °C 30 s	≥230 °C 40 s	≥230 °C 30 s
	≥217 °C 40 s	≥217 °C 40 s	≥217 °C 40 s	≥217 °C 40 s	≥217 °C 40 s	≥217 °C 65 s	≥217 °C 65 s
	≥200 °C 70 s	≥200 °C 70 s	≥200 °C 70 s	≥200 °C 70 s	≥200 °C 70 s	≥200 °C 90 s	≥200 °C 70 s
Time of reflow	2 times	2 times	1 time	2 times	1 time	2 times	2 times

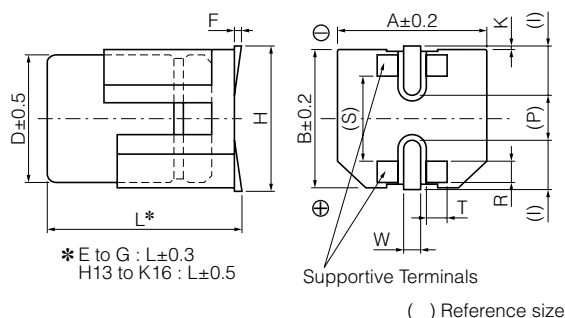
Reflow No.	Fig. (9)	Fig. (10)	Fig. (11)
Category	φ12.5 to φ18 (FK, TK, HD series) 6.3 V to 35 V	φ12.5 to φ18 (FK series) 50 V to 63 V (TK series) 50 V	φ12.5 to φ18 (FK series) 80 V to 100 V (TK series) 63 V to 100 V
Peak temperature	245 °C	245 °C	245 °C
Time in peak temperature	≥240 °C 30 s	≥240 °C 5 s	≥240 °C 5 s
Time in (*1) °C or more	≥217 °C 90 s	≥217 °C 30 s	≥217 °C 30 s
Time of reflow	2 times	2 times	1 time

* For reflow, use a thermal condition system such as infrared radiation (IR) or hot blast.

* Panasonic have several series available for pure Tin terminal and ZVEI reflow based on J-STD-020D (JEDEC).
(Please contact sales for details.)

■ Dimensions (Vibration-proof products)

* The size and shape are different from standard products. Please inquire details of our company.



(Unit : mm)

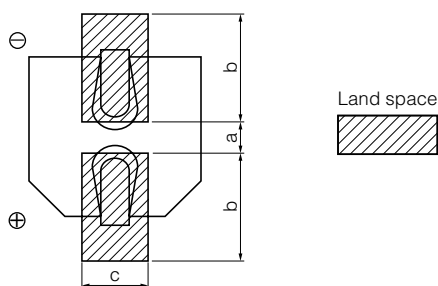
Size Code	φD	L	A, B	H max.	F	I	W	P	K	R	S	T
E	8.0	6.5	8.3	9.5	0 to +0.15	3.4	0.7±0.1	2.2	0.35 ^{+0.15} _{-0.20}	0.70±0.2	5.3±0.2	1.7±0.2
F	8.0	10.5	8.3	10.0	0 to +0.15	3.4	1.2±0.2	3.1	0.70±0.2	0.70±0.2	5.3±0.2	1.3±0.2
G	10.0	10.5	10.3	12.0	0 to +0.15	3.5	1.2±0.2	4.6	0.70±0.2	0.70±0.2	6.9±0.2	1.3±0.2
H13	12.5	13.8	13.5	15.0	-0.1 to +0.15	4.7	1.2±0.2	4.4	0.70±0.3	2.2±0.2	7.1±0.2	2.4±0.2
J16	16.0	16.8	17.0	19.0	-0.1 to +0.15	5.5	1.4±0.2	6.7	0.70±0.3	3.0±0.2	9.0±0.2	1.9±0.2
K16	18.0	16.8	19.0	21.0	-0.1 to +0.15	6.7	1.4±0.2	6.7	0.70±0.3	3.0±0.2	11.0±0.2	1.9±0.2

■ Land/Pad Pattern

The circuit board land/pad pattern size for chip capacitors is specified in the following table.

The land pitch influences installation strength and consider it.

● Standard products

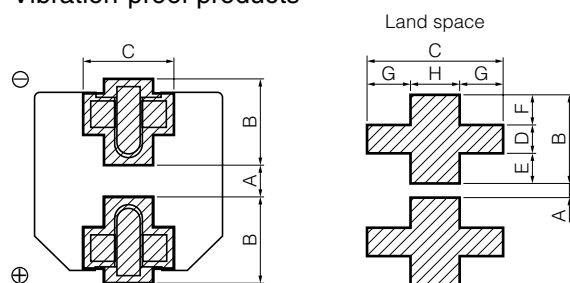


[Table of Board Land Size vs. Capacitor Size] (Unit : mm)

Size/Dimension	a	b	c
A (φ3)	0.6	2.2	1.5
B (φ4)	1.0	2.5	1.6
C (φ5)	1.5	2.8	1.6
D (φ6.3)	1.8	3.2	1.6
E (φ8 × 6.2L)	2.2	4.0	1.6
F (φ8 × 10.2L)	3.1	4.0	2.0
G (φ10 × 10.2L)	4.6	4.1	2.0
H (φ12.5)	4.0	5.7	2.0
J (φ16)	6.0	6.5	2.5
K (φ18)	6.0	7.5	2.5

* When size "a" is wide, back fillet can be made, decreasing fitting strength.

● Vibration-proof products



[Table of Board Land Size vs. Capacitor Size] (Unit : mm)

Size/Dimension	A	B	C	D	E	F	G	H
E (φ8 × 6.5L)	1.8	4.2	5.0	1.3	1.5	1.4	1.5	2.0
F (φ8 × 10.5L)	2.7	4.0	4.7	1.3	1.0	1.7	1.1	2.5
G (φ10)	3.9	4.4	4.7	1.3	1.2	1.9	1.1	2.5
H (φ12.5)	3.9	6.0	6.9	2.8	1.3	1.9	2.2	2.5
J (φ16)	5.8	6.8	6.2	3.6	1.3	1.9	1.7	2.8
K (φ18)	5.8	7.3	6.2	3.6	1.8	1.9	1.7	2.8

* When size "A" is wide, back fillet can be made, decreasing fitting strength.

* Take mounting conditions, solderability and fitting strength into consideration when selecting parts for your company's design.

■ Expected Life Estimate Quick Reference Guide

